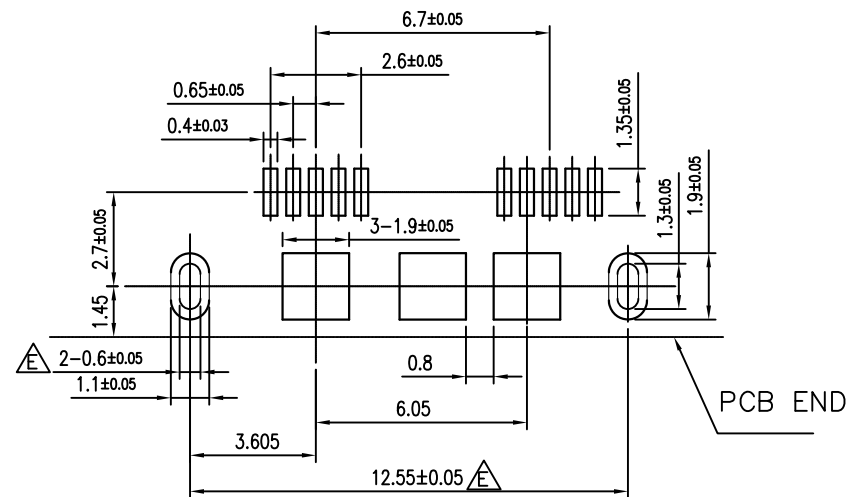
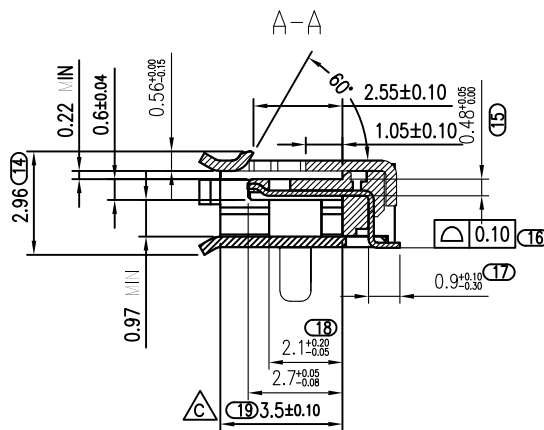
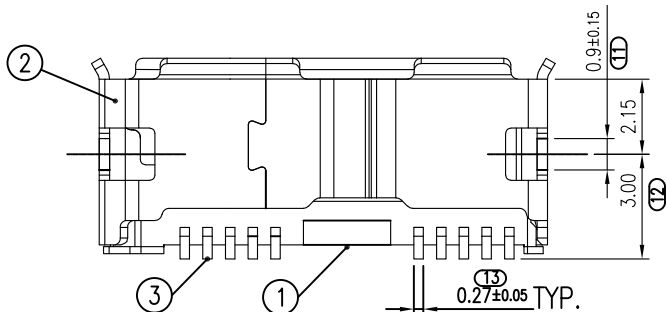
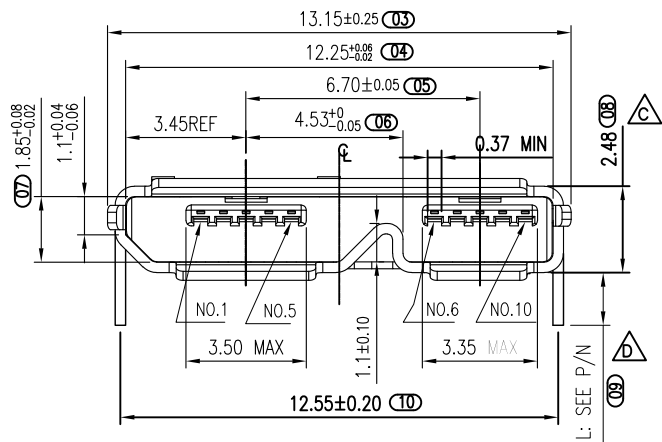
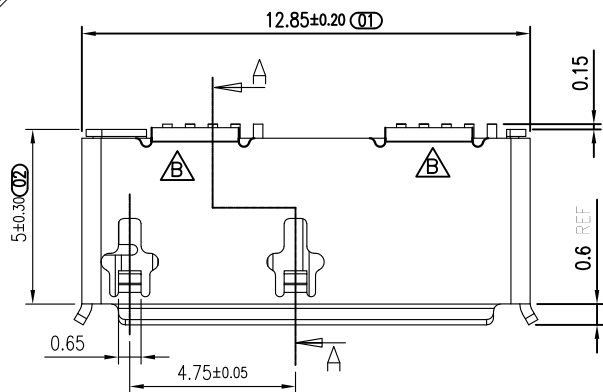




A  
B  
C  
D



NOTES:

- INSULATOR:LCP . COLOR-BLACK
- USB CONTACT: PHOSPHOR BRONZE,0.15mm THICKNESS, GOLD PLATED ON CONTACT AREA, GOLD FLASH OR 50 U" TIN PLATED ON SOLDER TAIL, 80 U" MIN. NICKEL UNDER PLATED OVERALL.
- SHELL: STAINLESS STEEL ,0.3 THICKNESS, 40U" NICKEL PLATED ON THE SOLDERING TAB.
- ELECTRICAL CHARACTERISTICS;
  - CONTACT RESISTANCE:30mΩ MAXIMUM
  - CONTACT CURRENT RATING:1.5AMPERES
  - DIELECTRIC WITHSTANDING VOLTAGE:100 V R.M.S.
  - INSULATION RESISTANCE 100 MΩ MIN
  - OPERATING TEMPERATURE:-40°C ~ 85°C
- MECHANICAL CHARACTERISTICS:
  - MATING FORCE:35N MAX
  - UNMATING FORCE:10N MIN(INITIAL)  
8N MIN(10000 CYCLES AFTER)
  - DURABILITY: 100,00 CYCLES MIN
- PRODUCT NO. DESCRIPTION:

Pin Assignments			
Shell	Shield	Pin No.	Signal Name
10	MicB_SSRX+	3	D+
9	MicB_SSRX-	2	D-
8	GND_DRAIN	1	VBUS
7	MicB_SSTX+	5	GND
6	MicB_SSTX-	4	ID
5	GND		
4	ID		

ITEM	DESCRIPTION	PIN NO.	SIGNAL NAME
3	CONTACT	3	D+
2	SHELL	2	D-
1	HOUSING	1	VBUS

TOLERANCE:		UNIT	深圳市创勤科技有限公司 Shenzhen Chuangqin Technology Co., Ltd.			
X. ± 0.50	X.* ± 1°	MM				
.X ± 0.30	.X* ± 1°	SHEET				
.XX ± 0.20	.XX* ± 1.0°	1/1				
.XXX ± 0.10		SCALE	DRAW:	LIN YUN	2010.12.13	P/N: CQ042-MF3S0511602
			DESIGN:			ITEM: Micro USB 3.0 B/F SMT (外壳间距12.55)
			CHECK:			DRW NO:
			APPR:			

A  
B  
C  
D

1 | 2 | 3 | 4 | 5 | 6